BERGQUIST GAP FILLER TGF 4000
Known as BERGQUIST GAP FILLER 4000
October 2018

PRODUCT DESCRIPTION
A thermally conductive, liquid gap filler material.

<table>
<thead>
<tr>
<th>Technology</th>
<th>Silicone</th>
</tr>
</thead>
<tbody>
<tr>
<td>Appearance (cured)</td>
<td>Blue</td>
</tr>
<tr>
<td>Appearance - Part A</td>
<td>Blue</td>
</tr>
<tr>
<td>Appearance - Part B</td>
<td>White</td>
</tr>
<tr>
<td>Cure</td>
<td>Room temperature cure or Heat cure</td>
</tr>
<tr>
<td>Application</td>
<td>Thermal management, TIM (Thermal Interface Material)</td>
</tr>
<tr>
<td>Mix Ratio by weight:</td>
<td>Part A: Part B 1 : 1</td>
</tr>
<tr>
<td>Mix Ratio by volume:</td>
<td>Part A: Part B 1 : 1</td>
</tr>
<tr>
<td>Solids Content, %</td>
<td>100</td>
</tr>
<tr>
<td>Operating Temperature Range</td>
<td>-60 to 200°C</td>
</tr>
</tbody>
</table>

FEATURES AND BENEFITS
- Thermal Conductivity: 4.0 W/m-K
- Extended working time for manufacturing flexibility
- Ultra-conforming, with excellent wet-out
- 100% solids - no cure by-products
- Excellent low and high temperature mechanical and chemical stability

BERGQUIST GAP FILLER TGF 4000 is a two-part, high thermal conductivity, liquid gap filling material. The mixed system will cure at room temperature and can be accelerated with the addition of heat. BERGQUIST GAP FILLER TGF 4000 offers an extended working time to allow greater flexibility in the customer's assembly process.

Liquid dispensed thermal materials offer infinite thickness variations and impart little to no stress on sensitive components during assembly. BERGQUIST GAP FILLER TGF 4000 exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required.

As cured, BERGQUIST GAP FILLER TGF 4000 provides a soft, thermally conductive, form-in place elastomer that is ideal for fragile assemblies and filling unique and intricate air voids and gaps.

TYPICAL APPLICATIONS
- Automotive electronics (HEV, NEV, batteries)
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink
- Telecommunications

TYPICAL PROPERTIES OF UNCURED MATERIAL
- Viscosity, High shear, Capillary, ASTM D5099, mPa·s (cP): 1,500/sec, Part A and B measured separately 50,000
- Density, ASTM D792, g/cc 3.1
- Working Time @ 25°C, Parallel plate rheometer, see reactivity application note, minutes 240
- Shelf Life @ 25°C, days 150

TYPICAL CURE SCHEDULE
- Cure Schedule
  24 hours @ 25°C
  30 minutes @ 100°C
- Parallel plate rheometer, see reactivity application note.

TYPICAL PROPERTIES OF CURED MATERIAL
<table>
<thead>
<tr>
<th>Physical Properties</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hardness, Shore 00, Thirty second delay value, ASTM D2240</td>
<td>75</td>
</tr>
<tr>
<td>Heat Capacity, ASTM D1269, J/g-K</td>
<td>0.8</td>
</tr>
<tr>
<td>Flammability, UL 94</td>
<td>V-0</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Electrical Properties</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dielectric Strength, ASTM D149, V/mil</td>
<td>450</td>
</tr>
<tr>
<td>Dielectric Constant, ASTM D150 @ 1,000 Hz</td>
<td>7.9</td>
</tr>
<tr>
<td>Volume Resistivity, ASTM D257, ohm-meter</td>
<td>1×10¹⁰</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Thermal Properties</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thermal Conductivity, ASTM D5470, W/(m-K)</td>
<td>4.0</td>
</tr>
</tbody>
</table>

GENERAL INFORMATION
For safe handling information on this product, consult the Safety Data Sheet, (SDS).

Not for product specifications
The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.
The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers’ experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

CONFIGURATIONS AVAILABLE
BERGQUIST GAP FILLER TGF 4000 is available in the following configurations:

- Cartridges
- Kits

STORAGE
Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5 to 25°C for a 5 month shelf life. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

\[\text{°C} \times 1.8 + 32 = \text{°F}\]
\[\text{kV/mm} \times 25.4 = \text{V/mil}\]
\[\text{mm} / 25.4 = \text{inches}\]
\[\text{N} \times 0.225 = \text{lb}\]
\[\text{N/mm} \times 5.71 = \text{lb/in}\]
\[\text{psi} \times 145 = \text{N/mm}^2\]
\[\text{MPa} = \text{N/mm}^2\]
\[\text{N} \times 0.738 = \text{lb-ft}\]
\[\text{N} \times 0.142 = \text{oz-in}\]
\[\text{mPa-s} = \text{cP}\]

Disclaimer

Note:
The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product. Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

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Reference 1

TDS BERGQUIST GAP FILLER TGF 4000, October 2018